



Product Change Notification: CENO-22NCXQ731

Date:

26-Jul-2026

Product Category:

16-Bit Microcontrollers, 32-Bit Microcontrollers

Notification Subject:

CCB 8383 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected PIC24FJ512GAxx, PIC24FJ128GBxx, PIC24FJ1024Gxx, PIC24FJ512GBxx, PIC24FJ256GBxx, PIC24FJ256GAxx, PIC24FJ128GAxx, PIC24FJ32GP2xx, PIC24FJ64GP2xx, PIC24FJ32GU2xx, PIC24FJ64GU2xx, PIC24FJ128GLxx, PIC24FJ64GL3xx, PIC24FJ256GUxx, PIC24FJ128GUxx, PIC24FJ512GLxx, PIC24FJ256GLxx, PIC24FJ512GUxx, PIC24FJ64GA7xx, PIC32MM0256Gxx, PIC32MM0128Gxx and PIC32MM0064Gxx device families available in various packages.

Affected CPNs:

[CENO-22NCXQ731_Affected_CPN_07262026.pdf](#)

[CENO-22NCXQ731_Affected_CPN_07262026.csv](#)

PCN Status: Final Notification

PCN Type: Manufacturing Change

Microchip Parts Affected: Please open one of the files found in the Affected CPNs section.

Note: For your convenience Microchip includes identical files in two formats (.pdf and .xls)

Description of Change: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected PIC24FJ512GAxx, PIC24FJ128GBxx, PIC24FJ1024Gxx, PIC24FJ512GBxx, PIC24FJ256GBxx, PIC24FJ256GAxx, PIC24FJ128GAxx, PIC24FJ32GP2xx, PIC24FJ64GP2xx, PIC24FJ32GU2xx, PIC24FJ64GU2xx, PIC24FJ128GLxx, PIC24FJ64GL3xx, PIC24FJ256GUxx, PIC24FJ128GUxx, PIC24FJ512GLxx, PIC24FJ256GLxx, PIC24FJ512GUxx, PIC24FJ64GA7xx, PIC32MM0256Gxx, PIC32MM0128Gxx and PIC32MM0064Gxx device families available in various packages at MTAI assembly site.

Pre and Post Summary Changes:

	Pre Change	Post Change	Change
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			(Yes/No)
Assembly Site	Microchip Technology Thailand (HQ) (MTAI)	Microchip Technology Thailand (HQ) (MTAI)	No
Wire Material	Au	CuPdAu	Yes
Die Attach Material	QMI519 (PFAS-free)	QMI519 (PFAS-free)	No
Molding Compound Material	G700HA	G700HA	No
Lead-Frame Material	C7025	C7025	No

Impacts to Datasheet: None

Change Impact: None

Reason for Change: To improve manufacturability by qualifying palladium coated copper with gold flash (CuPdAu) as a new bond wire material at MTAI assembly site.

Change Implementation Status: In Progress

Estimated First Ship Date: 07 October 2026 (date code: 2641)

Note Below EFSD: Please be advised that after the estimated first ship date customers may receive pre and post change parts.

Timetable Summary:

	July 2026					>	October 2026				
Work Week	27	28	29	30	31		40	41	42	43	44
Qual Report Availability				X							
Final PCN Issue Date				X							
Estimated Implementation Date								X			

Method to Identify Change: Traceability Code

Qualification Report: Please open the attachments included with this PCN labeled as PCN_#_Qual_Report.

Note: This is a qualification by similarity (QBS) to CCBs# 1769 and 7116.

Revision History:

July 26, 2026: Issued final notification.

Note: The change described in this PCN does not alter Microchip's current regulatory compliance regarding the material content of the applicable product.

Attachments:

[PCN_CENO-22NCXQ731 Qual Report_CCB 7116.pdf](#)

[PCN_CENO-22NCXQ731_Qual Report_CCB 1769.pdf](#)

Please contact your local [Microchip sales office](#) with questions or concerns regarding this notification.

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If you wish to change your PCN profile, including opt out, please go to the [PCN home page](#) select login and sign into your myMicrochip account. Select a profile option from the left navigation bar and make the applicable selections.

Affected Catalog Part Numbers (CPN):

PIC32MM0064GPM064-I/PT

PIC32MM0256GPM064-E/PT

PIC32MM0128GPM064-E/PT

PIC32MM0064GPM064-E/PT

PIC32MM0064GPM064T-I/PT

PIC24FJ512GA610-E/PT

PIC24FJ128GB610-I/PT

PIC24FJ1024GA610-E/PT

PIC24FJ512GB610-E/PT

PIC24FJ256GB610-E/PT

PIC24FJ256GA610-E/PT

PIC24FJ128GA610-E/PT

PIC24FJ32GP205-I/PT

PIC24FJ64GP205T-I/PT

PIC24FJ32GU205T-I/PT

PIC24FJ64GU205T-I/PT

PIC24FJ64GP205-I/PT

PIC24FJ32GU205-I/PT

PIC24FJ32GP205T-I/PT

PIC24FJ32GU205-E/PT

PIC24FJ32GP205-E/PT

PIC24FJ64GP205-E/PT

PIC24FJ64GU205-E/PT

PIC24FJ64GU205-I/PT

PIC24FJ128GL305-E/PT

PIC24FJ64GL305T-I/PT

PIC24FJ64GL305-E/PT

PIC24FJ64GL305-I/PT

PIC24FJ128GL305-I/PT

PIC24FJ128GL305T-I/PT

PIC24FJ128GL306-E/PT

PIC24FJ64GL306T-I/PT

CENO-22NCXQ731 - CCB 8383 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected PIC24FJ512GAxx, PIC24FJ128GBxx, PIC24FJ1024Gxx, PIC24FJ512GBxx, PIC24FJ256GBxx, PIC24FJ256GAxx, PIC24FJ128GAxx, PIC24FJ32GP2xx, PIC24FJ64GP2xx, PIC24FJ32GU2xx, PIC24FJ64GU2xx, PIC24FJ128GLxx, PIC24FJ64GL3xx, PIC24FJ128GL306T-I/PT

PIC24FJ64GL306-I/PT

PIC24FJ128GL306-I/PT

PIC24FJ64GL306-E/PT

PIC24FJ256GU405-E/PT

PIC24FJ128GU405-E/PT

PIC24FJ128GU405-I/PT

PIC24FJ512GL405-E/PT

PIC24FJ256GL405-E/PT

PIC24FJ128GL405-E/PT

PIC24FJ256GU405-I/PT

PIC24FJ512GL405-I/PT

PIC24FJ256GL405-I/PT

PIC24FJ128GL405-I/PT

PIC24FJ512GU405-E/PT

PIC24FJ256GU405T-I/PT

PIC24FJ128GU405T-I/PT

PIC24FJ256GL405T-I/PT

PIC24FJ512GU405T-I/PT

PIC24FJ512GL405T-I/PT

PIC24FJ128GL405T-I/PT

PIC24FJ512GU405-I/PT

PIC24FJ512GL410-E/PT

PIC24FJ512GU410-I/PT

PIC24FJ128GU410-I/PT

PIC24FJ512GL410-I/PT

PIC24FJ1024GA606T-I/PT

PIC24FJ512GL410T-I/PT

PIC24FJ256GL410T-I/PT

PIC24FJ128GL410T-I/PT

PIC24FJ256GU410-I/PT

PIC24FJ256GU408-I/PT

PIC24FJ128GL408T-I/PT

PIC24FJ128GU408-E/PT

PIC24FJ512GL408-E/PT

PIC24FJ256GL408-E/PT

PIC24FJ512GL408-I/PT

PIC24FJ512GU408-E/PT

PIC24FJ512GU408T-I/PT

PIC24FJ256GU408T-I/PT

PIC24FJ128GL408-E/PT

PIC24FJ512GL408T-I/PT

PIC24FJ256GL408T-I/PT

PIC24FJ128GU408T-I/PT

PIC24FJ256GU408-E/PT

PIC24FJ512GU408-I/PT

PIC24FJ128GU408-I/PT

PIC24FJ256GL408-I/PT

PIC24FJ128GL408-I/PT

PIC24FJ256GU406-I/PT

PIC24FJ128GU406-I/PT

PIC24FJ256GU406T-I/PT

PIC24FJ512GL406T-I/PT

PIC24FJ256GL406T-I/PT

PIC24FJ128GL406T-I/PT

PIC24FJ512GL406-I/PT

PIC24FJ256GL406-I/PT

PIC24FJ128GL406-I/PT

PIC24FJ256GU406-E/PT

PIC24FJ128GL406-E/PT

PIC24FJ128GU406T-I/PT

PIC24FJ128GU406-E/PT

PIC24FJ512GL406-E/PT

PIC24FJ256GL406-E/PT

PIC24FJ512GU406-I/PT

PIC24FJ512GU406T-I/PT

PIC24FJ512GU406-E/PT

PIC24FJ256GA804T-E/PT022

PIC24FJ256GA804T-E/PT021

PIC24FJ256GA804T-E/PT

PIC24FJ256GA704T-E/PT020

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PIC24FJ128GA704-E/PT

PIC24FJ256GA704-E/PT

PIC24FJ128GA704-I/PTC01

PIC24FJ256GA704-I/PT

PIC24FJ64GA704-I/PT

PIC24FJ128GA704-I/PT

PIC24FJ256GA704-E/PTC02

PIC32MM0256GPM064T-I/PT023

PIC32MM0256GPM064T-I/PT034

PIC32MM0128GPM064T-I/PT

PIC32MM0256GPM064T-I/PT

PIC32MM0256GPM064T-I/PTC21

PIC32MM0256GPM064-I/PT

PIC32MM0128GPM064-I/PT

PIC24FJ256GL410-I/PT

PIC24FJ128GL410-I/PT

PIC24FJ512GU410-E/PT

PIC24FJ256GU410-E/PT

PIC24FJ128GU410-E/PT

PIC24FJ256GL410-E/PT

PIC24FJ128GL410-E/PT

PIC24FJ512GU410T-I/PT

PIC24FJ256GU410T-I/PT

PIC24FJ128GU410T-I/PT

PIC24FJ256GB606T-I/PT

PIC24FJ512GA606T-I/PT

PIC24FJ256GA606T-I/PT

PIC24FJ128GB610-E/PT

PIC24FJ1024GB610-E/PT

PIC24FJ1024GA610-I/PTC01

PIC24FJ512GB610-I/PT

PIC24FJ256GB610-I/PT

PIC24FJ1024GB610-I/PT

PIC24FJ512GA610-I/PT

PIC24FJ256GA610-I/PT

PIC24FJ128GA610-I/PT
PIC24FJ1024GA610-I/PT
PIC24FJ512GA610T-I/PT
PIC24FJ256GB610T-I/PT
PIC24FJ1024GA610T-I/PTC01
PIC24FJ128GB610T-I/PT
PIC24FJ1024GB610T-I/PT
PIC24FJ128GA610T-I/PT
PIC24FJ1024GA610T-I/PT
PIC24FJ512GB610T-I/PT
PIC24FJ256GA610T-I/PT
PIC24FJ256GB606-I/PT
PIC24FJ512GB606-I/PT
PIC24FJ128GB606-I/PT
PIC24FJ1024GB606-I/PT
PIC24FJ512GA606-I/PT
PIC24FJ128GA606-I/PT
PIC24FJ1024GA606-I/PT
PIC24FJ512GB606T-I/PTC03
PIC24FJ128GA606-E/PT
PIC24FJ512GB606-E/PT
PIC24FJ1024GA606-E/PT
PIC24FJ256GB606-E/PT
PIC24FJ128GB606-E/PT
PIC24FJ1024GB606-E/PT
PIC24FJ512GA606-E/PT
PIC24FJ256GA606-E/PT
PIC24FJ512GB606T-I/PTC01
PIC24FJ512GB606T-I/PT
PIC24FJ128GA704T-I/PT
PIC24FJ256GA704T-E/PTC02
PIC24FJ64GA704T-I/PT
PIC24FJ256GA704T-I/PT
PIC24FJ128GA704T-I/PTC01
PIC32MM0256GPM064T-I/PT025

CENO-22NCXQ731 - CCB 8383 Final Notice: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected PIC24FJ512GAxx, PIC24FJ128GBxx, PIC24FJ1024Gxx, PIC24FJ512GBxx, PIC24FJ256GBxx, PIC24FJ256GAxx, PIC24FJ128GAxx, PIC24FJ32GP2xx, PIC24FJ64GP2xx, PIC24FJ32GU2xx, PIC24FJ64GU2xx, PIC24FJ128GLxx, PIC24FJ64GL3xx, PIC24FJ128GA606T-I/PT

PIC24FJ1024GB606T-I/PT

PIC24FJ128GB606T-I/PT

PIC24FJ1024GB606-I/PTC02

PIC24FJ256GA606-I/PT

PIC24FJ512GB606-I/PTC03



QUALIFICATION REPORT SUMMARY
RELIABILITY LABORATORY

PCN #: CENO-22NCXQ731

Date:
November 25, 2024

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected PIC24FJ512GAxx, PIC24FJ128GBxx, PIC24FJ1024Gxx, PIC24FJ512GBxx, PIC24FJ256GBxx, PIC24FJ256GAxx, PIC24FJ128GAxx, PIC24FJ32GP2xx, PIC24FJ64GP2xx, PIC24FJ32GU2xx, PIC24FJ64GU2xx, PIC24FJ128GLxx, PIC24FJ64GL3xx, PIC24FJ256GUxx, PIC24FJ128GUxx, PIC24FJ512GLxx, PIC24FJ256GLxx, PIC24FJ512GUxx, PIC24FJ64GA7xx, PIC32MM0256Gxx, PIC32MM0128Gxx and PIC32MM0064Gxx device families available in various packages.



MICROCHIP PACKAGE QUALIFICATION REPORT

Purpose Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected PIC24FJ512GAxx, PIC24FJ128GBxx, PIC24FJ1024Gxx, PIC24FJ512GBxx, PIC24FJ256GBxx, PIC24FJ256GAxx, PIC24FJ128GAxx, PIC24FJ32GP2xx, PIC24FJ64GP2xx, PIC24FJ32GU2xx, PIC24FJ64GU2xx, PIC24FJ128GLxx, PIC24FJ64GL3xx, PIC24FJ256GUxx, PIC24FJ128GUxx, PIC24FJ512GLxx, PIC24FJ256GLxx, PIC24FJ512GUxx, PIC24FJ64GA7xx, PIC32MM0256Gxx, PIC32MM0128Gxx and PIC32MM0064Gxx device families available in various packages.

CN E000240628
QUAL ID R2401107 Rev. A
MP CODE TLAk14V7XQEF
Part No. DSPIC33EP512GM710-E/PT
Bonding No. BD-002574 Rev. 01
CCB No. 7116

Package

Type 100L TQFP
Package size 12 x 12 mm

Lead Frame

Paddle size 240 x 240 mils
Material C7025
Surface Bare Cu
Process Stamped
Lead Lock No
Part Number 10110002
Treatment BOT

Material

Epoxy QMI519
Wire CuPdAu
Mold Compound G700HA
Plating Composition Matte Sn



MICROCHIP

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI251901814.000	TC11925144269.210	2432U5E
MTAI252000203.000	TC11925144269.200	2433U5C
MTAI252000528.000	TC11925144269.220	2433VGD

Result

☒ Pass ☐ Fail ☐ _____

100L TQFP (12x12 mm) assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020E standard.

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS	Result	Remarks
<u>Precondition</u> <u>Prior Perform</u> <u>Reliability Tests</u> (At MSL Level 1)	Electrical Test: +25°C, 85°C, 125°C and 150°C System: J750 Bake 150°C, 24 hrs. System: CHINEE 85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243	JESD22-A113 JIP/ IPC/JEDEC J-STD-020E	693(0)	0/693		Good Devices
	Electrical Test: +25°C, 85°C, 125°C and 150°C System: J750		693(0)	0/693	Pass	

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
Temp Cycle	Stress Condition: -65°C to +150°C, 500 Cycles System: TABAI ESPEC TSA-70H Electrical Test: +85°C, 125°C and 150°C System: J750 Bond Strength: Wire Pull (>3.00 grams)	JESD22-A104	231(0) 15(0)	0/231 0/231 0/15	Pass Pass	Parts had been pre-conditioned at 260°C 77 units / lot
UNBIASED-HAST	Stress Condition: +130°C/85%RH, 96 hrs. System: HAST 6000X Electrical Test: +25°C System: J750	JESD22-A118	231(0)	0/231 0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot
HAST	Stress Condition: +130°C/85%RH, 96 hrs. Bias Volt: VDD=3.6 Volts System: HAST 6000X Electrical Test: +25°C, 85°C, 125°C and 150°C System: J750	JESD22-A110	231(0)	0/231 0/231	Pass	Parts had been pre-conditioned at 260°C 77 units / lot

PACKAGE QUALIFICATION REPORT

Test Number (Reference)	Test Condition	Standard/ Method	Qty. (Acc.)	Def/SS.	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs. System: TPS Bake Oven	JESD22- A103		0/135		45 units / lot
	Electrical Test: +25°C, 85°C, 125°C and 150°C System: J750		135(0)	0/135	Pass	
Bond Strength Data Assembly	Wire Pull (>3.00 grams)	Mil. Std. 883-2011	30(0) Wires	0/30	Pass	
	Bond Shear (>12.60 grams)	CDF-AEC- Q100-001	30(0) bonds	0/30	Pass	



Qualification Report Summary

RELIABILITY LABORATORY

PCN #: CENO-22NCXQ731

Date: June 26, 2026

Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected PIC24FJ512GAxx, PIC24FJ128GBxx, PIC24FJ1024Gxx, PIC24FJ512GBxx, PIC24FJ256GBxx, PIC24FJ256GAxx, PIC24FJ128GAxx, PIC24FJ32GP2xx, PIC24FJ64GP2xx, PIC24FJ32GU2xx, PIC24FJ64GU2xx, PIC24FJ128GLxx, PIC24FJ64GL3xx, PIC24FJ256GUxx, PIC24FJ128GUxx, PIC24FJ512GLxx, PIC24FJ256GLxx, PIC24FJ512GUxx, PIC24FJ64GA7xx, PIC32MM0256Gxx, PIC32MM0128Gxx and PIC32MM0064Gxx device families available in various packages.

PACKAGE QUALIFICATION REPORT

Purpose: Qualification of palladium coated copper with gold flash (CuPdAu) as a new bond wire material for selected PIC24FJ512GAxx, PIC24FJ128GBxx, PIC24FJ1024Gxx, PIC24FJ512GBxx, PIC24FJ256GBxx, PIC24FJ256GAxx, PIC24FJ128GAxx, PIC24FJ32GP2xx, PIC24FJ64GP2xx, PIC24FJ32GU2xx, PIC24FJ64GU2xx, PIC24FJ128GLxx, PIC24FJ64GL3xx, PIC24FJ256GUxx, PIC24FJ128GUxx, PIC24FJ512GLxx, PIC24FJ256GLxx, PIC24FJ512GUxx, PIC24FJ64GA7xx, PIC32MM0256Gxx, PIC32MM0128Gxx and PIC32MM0064Gxx device families available in various packages.

CN: BC151737
QUAL ID: Q15121 Rev. A
MP CODE: SAAA17V7XEXF
Part No.: PIC24FJ1024GB610-I/PT
Bonding No.: BDE-002698 Rev. 04
CCB No.: 1769

Lead Frame

Paddle Size: 240 x 240 mils
Material: C7025
Surface: Bare copper on paddle
Process: Stamp
Lead Lock: No
Part Number: 10110002
Plating Composition: Matte Tin
Treatment Brown Oxide Treatment

Bond Wire

Wire: CuPdAu wire

Die Attach Material

Epoxy: 3280

Mold Compound

Mold Compound: G700HA

Package

Type: 100L TQFP
Package Size: 12X12x1.0 mm

PACKAGE QUALIFICATION REPORT

Manufacturing Information

Assembly Lot No.	Wafer Lot No.	Date Code
MTAI162001904.000	SCB1916096510.111	1533Y15
MTAI162002163.000	SCB1916096510.111	1533052
MTAI162002206.000	SCB1916096510.111	153306P

Result: **Pass**

Conclusion:

100L TQFP (12x12x1 mm) assembled by MTAI pass reliability test per QCI-39000. This package was qualified the Moisture/Reflow Sensitivity Classification Level 1 at 260°C reflow temperature per IPC/JEDEC J-STD-020D standard.

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Moisture/Reflow Sensitivity Classification Test (At MSL Level 1)	85°C/ 85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH 3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243	IPC/JEDEC J-STD-020D	135	0/135	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Precondition Prior Perform Reliability Tests (At MSL Level 1)	Electrical Test :+25°C and 85°C System: J750	JESD22-A113	693(0)	693		Good Devices
	Bake 150°C, 24 hrs System: CHINEE			693		
	85°C/85%RH Moisture Soak 168 hrs. System: TABAI ESPEC Model PR-3SPH			693		
	3x Convection-Reflow 265°C max System: Vitronics Soltec MR1243			693		
	Electrical Test :+25°C and 85°C System: J750			0/693	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Temp Cycle	Stress Condition: (Standard) -65°C to +150°C, 500 Cycles System : TABAI ESPEC TSA-70H	JESD22-A104		231		Parts had been pre-conditioned at 260°C
	Electrical Test: + 85°C System: J750		231(0)	0/231	Pass	
	Wire Pull (> 2.5 grams)	M2011	15(0)	0/15	Pass	
	Bond Shear (>15.00 grams)		15(0)	0/15	Pass	

PACKAGE QUALIFICATION REPORT

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
UNBIASED-HAST	Stress Condition: (Standard) +130°C/85%RH, 96 hrs. System: HAST 6000X	JESD22-A118		231		Parts had been pre-conditioned at 260°C
	Electrical Test: +25°C System: J750		231(0)	0/231	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
HAST	Stress Condition: (Standard) +130°C/85%RH, 96 hrs. Bias Volt: 2.5 Volts System: HAST 6000X	JESD22-A110		231		Parts had been pre-conditioned at 260°C
	Electrical Test: + 25°C and 85°C System: J750		231(0)	0/231	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
High Temperature Storage Life	Stress Condition: Bake 175°C, 504 hrs System: SHEL LAB	JESD22-A103		45		45 units
	Electrical Test :+25°C and 85°C System: J750		45(0)	0/45	Pass	

Test	Test Condition	Standard / Method	Qty. (Acc.)	Def/SS	Result	Remarks
Bond Strength Data Assembly	Wire Pull (> 2.5 grams)	M2011	30(0)	0/30	Pass	
	Bond Shear (>15.00 grams)	JESD22-B116	30(0)	0/30	Pass	